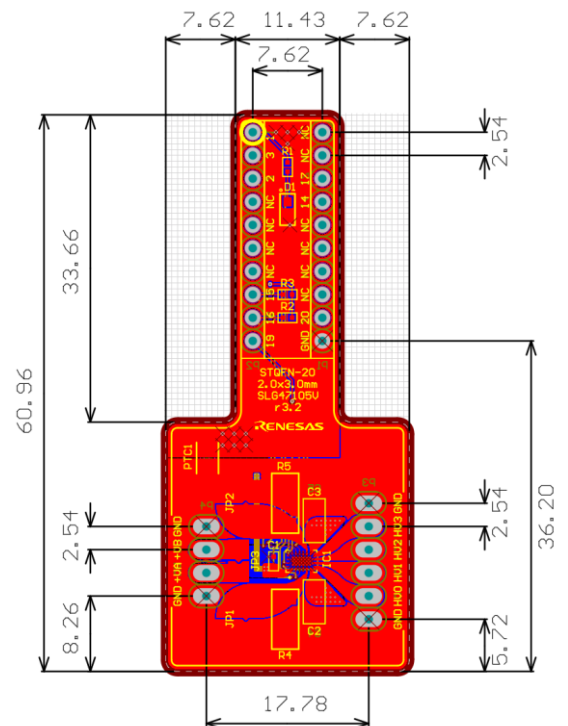


1. Description

The GreenPAK DIP Adapter is a small PCB that lets you adapt STQFN packages into a DIP footprint. This board can speed up your design prototyping and testing. This small board 0.90x2.20 inch uses 20 pins DIP footprint with 0.3 inch width. You can also use this adapter for prototyping by making STQFN package compatible with solder free breadboards.

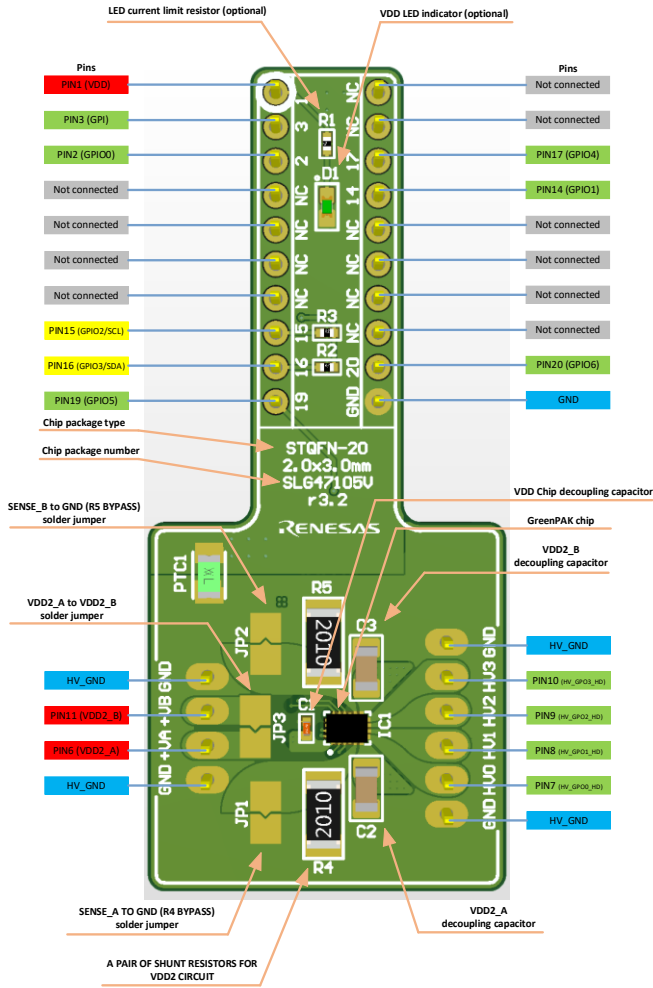
2. Features

- Low cost
- Simplifies prototyping of SMT IC's
- Four high voltage high current output GPOs
- Current up to 1 A per HV GPO
- Current sensing resistors
Variable current sensing configurations
- Optional V_{DD} LED indicator
- Decoupling capacitor included
- Screw terminals for high voltage high and current lines
- Optional I²C pull-up resistors

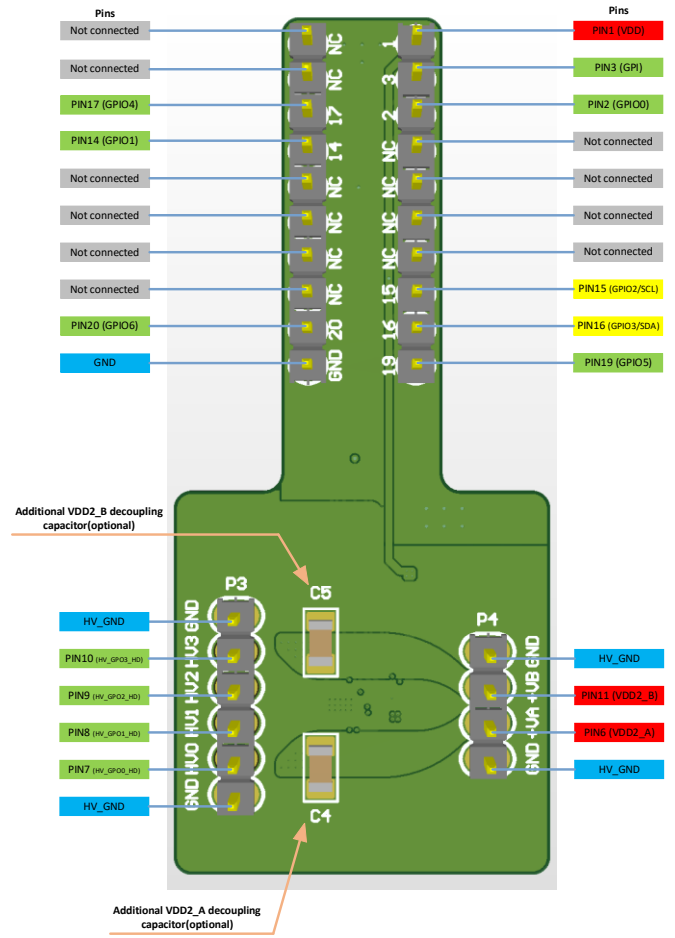


Note 1 All sizes in millimeters (mm).

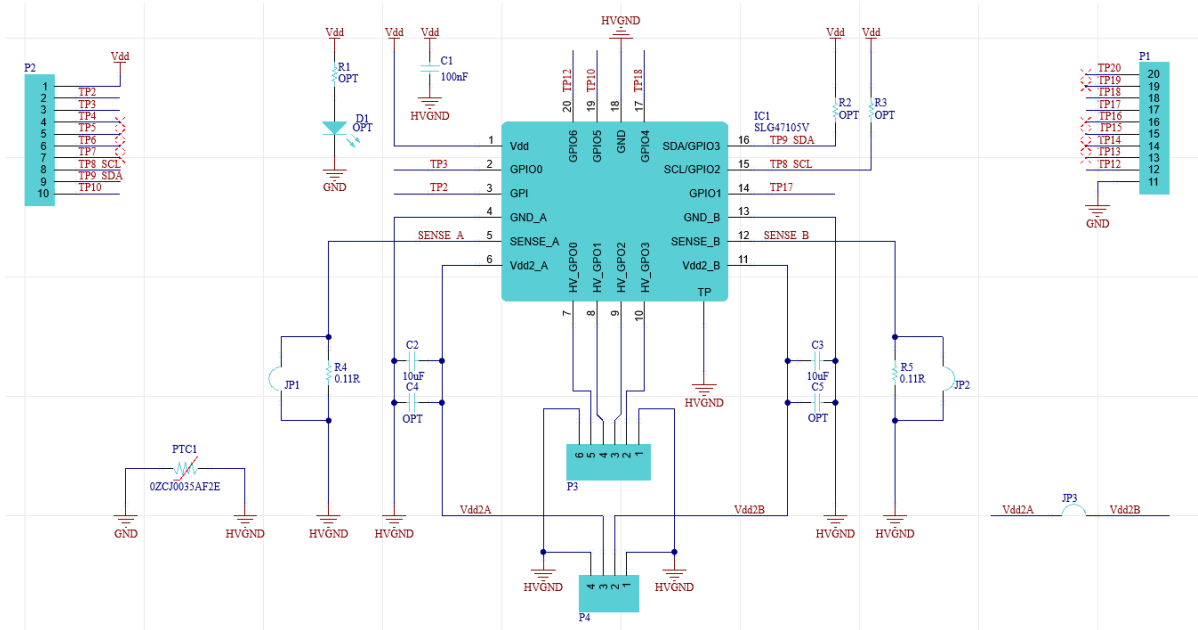
3. Top View



4. Bottom View



5. Board Schematic



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